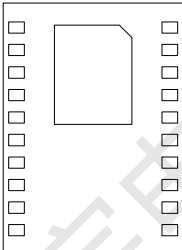
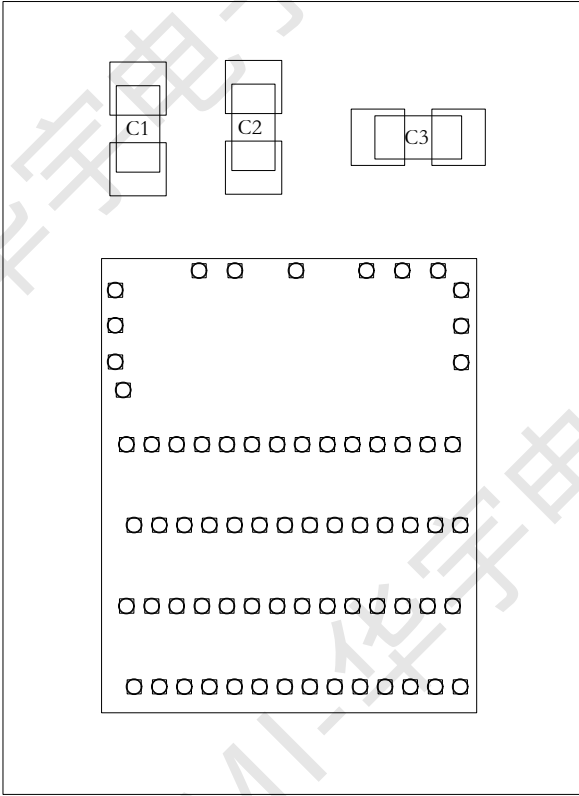


 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram				客户代码 Customer No.	1241	线图号 Drawing No.	HY-PX-1241-005 A	页码 Page 1 / 3
				产品名称 Product Type	JW6109L	封装外型 PKG Type	FCLGA5L(4.0X5.5X0.75-P0.5)	
助焊剂 Flux	橡胶吸嘴 pick collet	钨钢吸嘴 bond collet	蘸胶盘 flux plate	顶针 ejector	植球助焊剂 Ball Flux	塑封料型号(绿色环保) Compound Type (Green)	基板编码 Substrate No.	
TACFlux026S	NA	NA	40UM	5mil	-	首选(Preferred): G311ACC 备选(Optional):	FCLGA5L(040550)1241001	
客户图号 Customer drawing NO.								

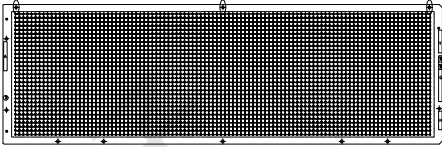
PIN 1



PIN 1

底部示意图

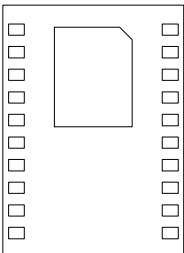
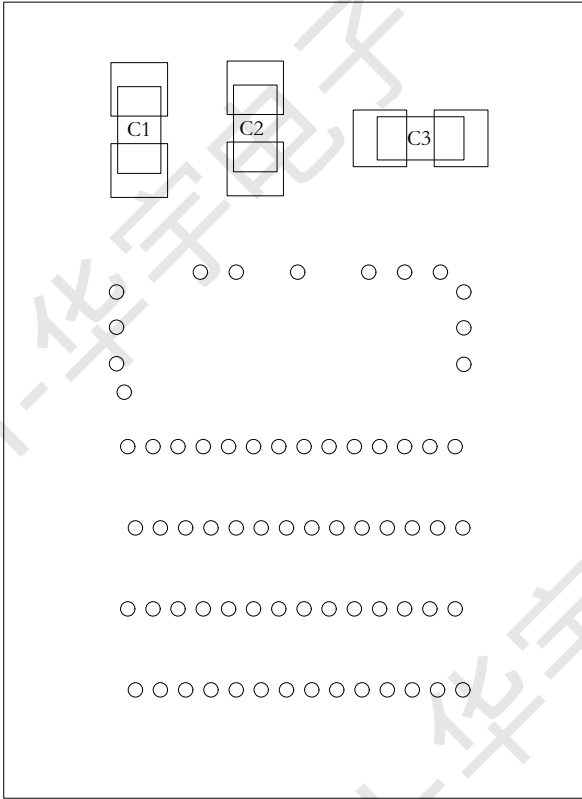
注意：
1.后切割道宽度0.2mm。

框架传送方向（装片）： L/F Direction (D/A)：圆孔朝上			实物图： Chip photo:			特殊说明 Special Instructions： DB注意： 1.装片位置公差为±25um；	
							
芯片名称： Die Name:	JW_S35	晶圆尺寸 Wafer Size	8 inch	UBM 尺寸 UBM Size(um)：	98	基板焊盘阻焊开口： Pad S/M Opening of Substrate:	100
Chip ID	JM1011	是否激光切割 If laser ?	否	最小凸点节距： Min Bump Pitch(um)：	174	凸点高度 BumpComposition(um)：	5Cu+3Ni+80SnAg
芯片尺寸： Die Size	2600*3150 (μ m²) 102.36*124.02 (mil²)	晶圆工艺节点： Wafer Node(nm)：	--	凸点尺寸： Bump Size:	110	凸点数量： No. of Bump:	69
划片道宽度 Street line (μ m)	80	减薄厚度 (μ m) Wafer Thickness	200(不带植球)	凸点类型： Bump Type：	PI+Solder	散热片/塑封体厚度 (um) HS/Mold Thickness:	500
pad下是否有电路	是/YES	基板编号 Substrate number	FCLGA5L(040550)1241001	基板焊盘尺寸： Bump pad size(um)：	135	基板厚度 (um) Substrate Thickness:	250
拟制 Prepared by		制图日期 Create Date	2025/7/8	生效日期 Effective Date		客户确认签字/盖章： Customer Signature	
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by			

*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！

*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

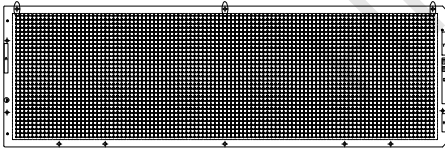
PIN 1



PIN 1

底部示意图

框架传送方向（装片）：
L/F Direction (D/A)：上侧三个圆孔



实物图：
Chip photo:



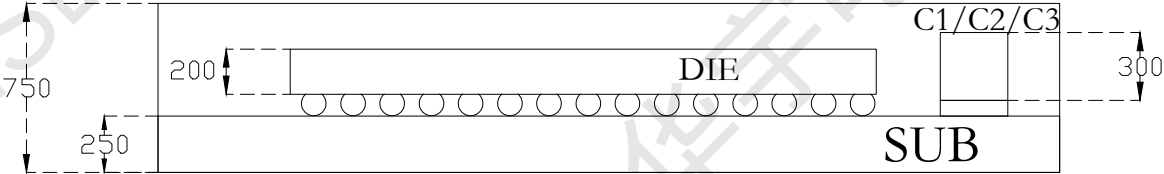
特殊说明 Special Instructions：

SMT注意：
1.控制溢锡，防止沾锡。

NO.	Item	Reference	value	size	package	KD P/N	Quantity
1	C1	/	0201/100NF/104K/10%/X5R/100V		0201		1
2	C2/C3	/	0201/1UF/105K/10%/X7R/100V		0201		2
3	基板	FCLGA5L(040550)1241001	基板	240X76. 3X0. 25mm	/		1
4	锡膏	/	F590 SnCu0. 7-89M4		/		/
SMT元器件总计							2

拟制 Prepared by		制图日期 Create Date	2025/7/8	生效日期 Effective Date		客户确认签字/盖章： Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

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拟制 Prepared by		制图日期 Create Date	2025/7/8	生效日期 Effective Date		客户确认签字/盖章: Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

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